

# United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/505,287	08/19/2004	Willem Jan Toren	FR02 0010 US	5180	
7590 05/25/2006			EXAMI	EXAMINER	
Philips Electronics North America Corporation			CHEN, ERI	CHEN, ERIC BRICE	
Intellectual Property & Standards 1109 McKay Drive M/S41-SJ San Jose, CA 95131			ART UNIT	PAPER NUMBER	
			1765		
			DATE MAILED: 05/25/2006		

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)			
Office Action Summer:	10/505,287	TOREN, WILLEM JAN			
Office Action Summary	Examiner	Art Unit			
	Eric B. Chen	1765			
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address			
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DATE of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication.  If NO period for reply is specified above, the maximum statutory period value and the reply within the set or extended period for reply will, by statute any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tin will apply and will expire SIX (6) MONTHS from , cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed on 19 A	<u>ugust 2004</u> .	•			
<i>;</i>	,				
Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 4	53 O.G. 213.			
Disposition of Claims					
<ul> <li>4)  Claim(s) 1-13 is/are pending in the application 4a) Of the above claim(s) 10-13 is/are withdraw</li> <li>5)  Claim(s) is/are allowed.</li> <li>6)  Claim(s) 1-9 is/are rejected.</li> <li>7)  Claim(s) is/are objected to.</li> <li>8)  Claim(s) 1-13 are subject to restriction and/or expressions.</li> </ul>	vn from consideration.				
Application Papers					
9) The specification is objected to by the Examine 10) The drawing(s) filed on is/are: a) acc Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex	epted or b) objected to by the drawing(s) be held in abeyance. Se tion is required if the drawing(s) is ob	e 37 CFR 1.85(a). ojected to. See 37 CFR 1.121(d).			
	tammer, Note the attached Office	Action of form 1 10 102.			
Priority under 35 U.S.C. § 119  12) △ Acknowledgment is made of a claim for foreign a) △ All b) ☐ Some * c) ☐ None of:  1. ☐ Certified copies of the priority document 2. ☐ Certified copies of the priority document 3. △ Copies of the certified copies of the priority application from the International Bureat * See the attached detailed Office action for a list	s have been received. s have been received in Applicat rity documents have been receive u (PCT Rule 17.2(a)).	ion No ed in this National Stage			
Attachment(s)					
1) Notice of References Cited (PTO-892)	4) Interview Summary				
<ol> <li>Notice of Draftsperson's Patent Drawing Review (PTO-948)</li> <li>Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date <u>8/19/04</u>.</li> </ol>	Paper No(s)/Mail D 5) Notice of Informal f 6) Other:	ate Patent Application (PTO-152)			
	<del></del>				

#### **DETAILED ACTION**

## Election/Restrictions

1. Restriction is required under 35 U.S.C. 121 and 372.

This application contains the following inventions or groups of inventions which are not so linked as to form a single general inventive concept under PCT Rule 13.1.

In accordance with 37 CFR 1.499, applicant is required, in reply to this action, to elect a single invention to which the claims must be restricted.

Group I, claims 1-9, drawn to a method of forming electrical connections.

Group II, claims 10-12, drawn to an integrated circuit.

Group III, claim 13, drawn to an electrical or electronic device.

- 2. The inventions listed as Groups I-III do not relate to a single general inventive concept under PCT Rule 13.1 because, under PCT Rule 13.2, they lack the same or corresponding special technical features for the following reasons: Group II requires that the intermediate layer is flush with an edge of the apertures, a feature not claimed in Groups I and II; Group III encompasses an entire electrical device, which includes components other than the integrated circuit.
- 3. During a telephone conversation with Peter Zawilski on May 16, 2006, a provisional election was made without traverse to prosecute the invention of Group I, claims 1-9. Affirmation of this election must be made by applicant in replying to this Office action. Claims 10-13 are withdrawn from further consideration by the examiner, 37 CFR 1.142(b), as being drawn to a non-elected invention.

Art Unit: 1765

## **Priority**

4. Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

# Claim Rejections - 35 USC § 102

5. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (a) the invention was known or used by others in this country, or patented or described in a printed publication in this or a foreign country, before the invention thereof by the applicant for a patent.
- 6. Claims 1-3 and 7-9 are rejected under 35 U.S.C. 102(b) as being anticipated by Hause et al. (U.S. Patent No. 5,843,625).
- 7. As to claim 1, Hause discloses a method of forming electrical connections on a substrate (column 1, lines 9-13), comprising the following steps: a) depositing an intermediate layer of material (104/106) on a substrate (100) (column 6, lines 15-41; Figure 2), b) forming an etching mask (108) on the intermediate layer (104/106) (column 6, lines 42-45), said mask (108) having at least one window (column 6, lines 47-49; Figure 3) having dimensions which are larger than the dimensions envisaged for the electrical connections to be realized (column 6, lines 47-49; column 8, lines 36-44), c) etching the intermediate layer of material (104/106) through the window of the mask (108) in order to form therein at least one aperture (110), having lateral side-walls (111) (column 6, lines 55-62), for receiving the electrical connections (column 8, lines 9-11; Figure 8), d) coating the lateral side-walls of the aperture with a spacer (114) in order to

Application/Control Number: 10/505,287

Art Unit: 1765

narrow the aperture (column 7, lines 28-33; column 8, lines 36-44), e) depositing at least one conductor material (125) so as to fill the narrowed aperture (column 8, lines 9-11; Figure 8), and f) performing an abrasion operation in order to remove excess conductor material outside the narrowed aperture (column 8, lines 25-31).

Page 4

- 8. As to claim 2, Hause discloses that the step a) utilizes a dielectric material for forming the intermediate layer (104/106) (column 6, lines 15-24, lines 37-39) while a metallic conductor material is used in the step e) (column 8, lines 22-23).
- 9. As to claim 3, Hause discloses that the step d) comprises the deposition of a layer of an insulating coating material (column 7, lines 12-15), followed by the anisotropic etching of this layer so as to preserve a part thereof on the side-walls of the aperture (column 7, lines 19-21; Figure 6).
- 10. As to claim 7, Hause discloses that apertures are etched which extend right through the intermediate layer (104/106) (Figure 7).
- 11. As to claim 8, Hause discloses the mask (108) is formed by means of a photolithography technique (column 6, lines 49-53), and in which the narrowed apertures have dimensions (d) which are referred to as "ultimate" dimensions which are smaller than those that can be achieved by means of said photolithography technique (column 8, lines 36-44).
- 12. As to claim 9, Hause discloses that the electrical connections comprise wiring tracks and/or terminals and/or vias between layers (column 8, lines 9-11; Figure 8).

Application/Control Number: 10/505,287 Page 5

Art Unit: 1765

## Claim Rejections - 35 USC § 103

- 13. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 14. Claims 4-6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hause, in view of Wolf, Silicon Processing for the VLSI Era, Vol. 4, Lattice Press (2002).
- 15. As to claim 4, Hause does not expressly disclose that the side-walls of the aperture are coated by means of a dielectric material having a low dielectric constant (k). However, Wolf teaches that low-k dielectric films are important in integrated circuit applications because they can significantly improve circuit performance characteristics (page 639). Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to use a dielectric material having a low dielectric constant (k). One who is skilled in the art would be motivated to use a material that can significantly improve circuit performance characteristics.
- 16. As to claim 5, Hause does not expressly disclose that the dielectric material of the coating layer is chosen from among fluorous glass, glass deposited by spinning and silicon oxide containing carbon. Wolf teaches that silicon oxide containing carbon (or C-dope oxide (Si-O-C)) is a commonly used low-k material (page 646, Table 14-3). Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to use a dielectric material of the coating layer chosen from silicon oxide containing carbon. One who is skilled in the art would be motivated to use a

Application/Control Number: 10/505,287

Art Unit: 1765

commonly used low-k material, known to possess the characteristics to be successfully

Page 6

used in an integrated circuit.

17. As to claim 6, Hause discloses that the window of the mask (108) registers with at least one active part of the substrate (102) (column 6, lines 7-14) (from Figure 3, the window in mask (108) overlies (102). Hause does not expressly disclose that said active part of the substrate (102) is exposed during the etching of the intermediate layer of material through the window of the mask (Figure 4). However, Hause discloses that (104) is silicon oxide (column 6, lines 15-18). Additionally, Wolf teaches that low-k dielectric films (i.e., k < 3.9 for silicon oxide) are important in integrated circuit applications because they can significantly improve circuit performance characteristics (page 639). Thus, there is a suggestion for exposing the active part of the substrate (102) during the etching of the intermediate layer of material through the window of the mask, because performing this step would reduce the volume of silicon oxide, replacing this material with the low-k dielectric side-walls, as in the combined teachings. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to expose the active part of the substrate during the etching of the intermediate layer of material through the window of the mask.

#### Conclusion

18. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Chang (U.S. Patent Appl. Pub. No. 2002/0137331) discloses forming sidewalls in an aperture to reduce its dimensions.

Application/Control Number: 10/505,287

Art Unit: 1765

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Eric B. Chen whose telephone number is (571) 272-2947. The examiner can normally be reached on Monday through Friday, 8AM to 4:30PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine G. Norton can be reached on (571) 272-1465. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

EBC

May 18, 2006

SHAMIM AHMED PRIMARY EXAMINER Page 7